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CM1282-01D1

1-Channel Ultra-Low Capacitance ESD Protection Device

Product Description

The CM1282-01D1 is an ultra-low capacitance, 1-channel ESD protection device. The CM1282-01D1 is fully compliant with IEC 61000-4-2 and is also RoHS-compliant.

Features

- 1 Channel ESD Protection
- Provides In-System ESD Protection to IEC61000-4-2 Level 4
 - ± 8 kV Contact Discharge
- Back-to-Back Diode (I/O-to-I/O Configuration)
- Compact DSN2 (1 mm x 0.6 mm x 0.5 mm) Package Saves Board Space and Facilitates Layout in Space-Critical Applications
- These Devices are Pb-Free and are RoHS Compliant

Applications

ESD Protection for Static-Sensitive Electronic Equipment such as:

- Wireless Handsets
- Handheld PCs/PDAs
- MP3 Players
- Digital Camcorders
- Notebooks
- Desktop PCs



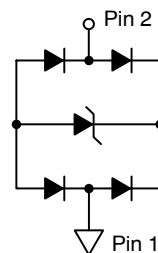
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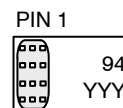


DSN2
D1 SUFFIX
CASE 152AE

ELECTRICAL SCHEMATIC



MARKING DIAGRAM



94 = Specific Device Code
YYY = Year Code

ORDERING INFORMATION

Device	Package	Shipping [†]
CM1282-01D1	DSN2 (Pb-Free)	5000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1282-01D1

PACKAGE / PINOUT DIAGRAM

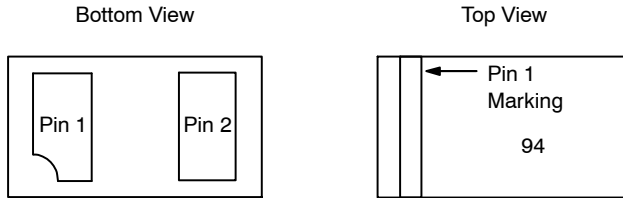


Table 1. PIN DESCRIPTIONS

1-Channel DSN2 Package			
Pin	Name	Type	Description
1	V_N	GND	Ground
2	CH	I/O	ESD Channel

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
Package Power Dissipation	450	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature	-40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{BR}	Reverse Breakdown Voltage	$I_{IN} = \pm 10$ mA	± 7.5	± 9.0	± 11.0	V
I_{LEAK}	Channel Leakage Current	$V_{IN} = \pm 5$ V		0.1	1.0	μ A
C_{IN}	Channel Input Capacitance	At 1 MHz, $V_{IN} = 0$ V		0.5	0.6	pF
V_{ESD}	ESD Protection (Peak Discharge Voltage at any Channel Input, in System): Contact Discharge per IEC 61000-4-2 Standard	(Note 2)	8			kV
V_{CL}	Channel Clamp Voltage	$I_{PP} = \pm 1$ A, $t_P = 8/20$ μ s		11		V
R_{DYN}	Dynamic Resistance	$I_{PP} = \pm 1$ A, $t_P = 8/20$ μ s		1.2		Ω

1. All parameters specified at $T_A = 25^\circ\text{C}$ unless otherwise noted.

2. Standard IEC 61000-4-2 with $C_{Discharge} = 150$ pF, $R_{Discharge} = 330$ Ω

CM1282-01D1/D